



京微雅格
Capital Microelectronics



嵌入式系统联谊会
www.esbf.org.cn

FPGA发展的昨天、今天和明天

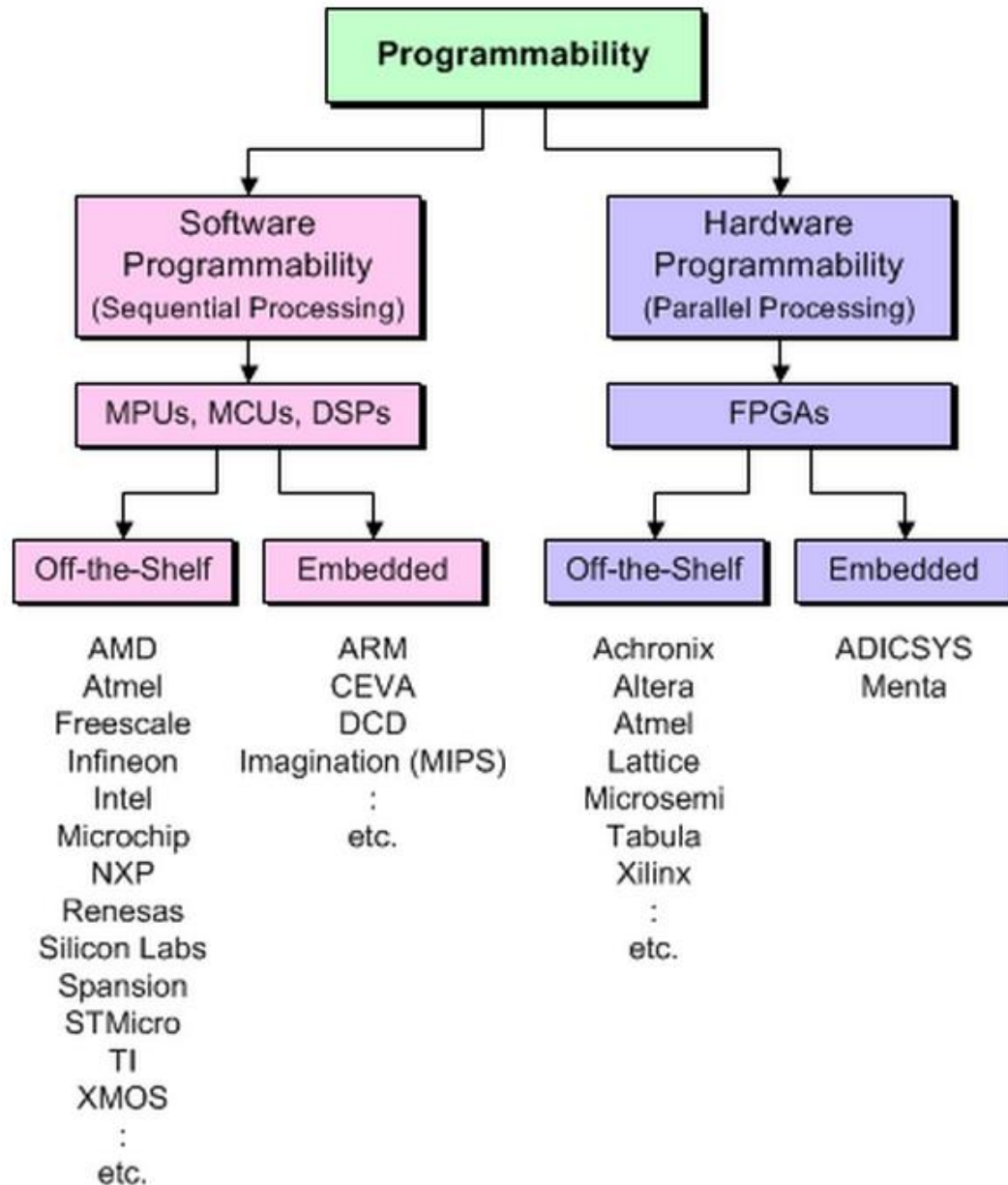
副总裁：王海力博士

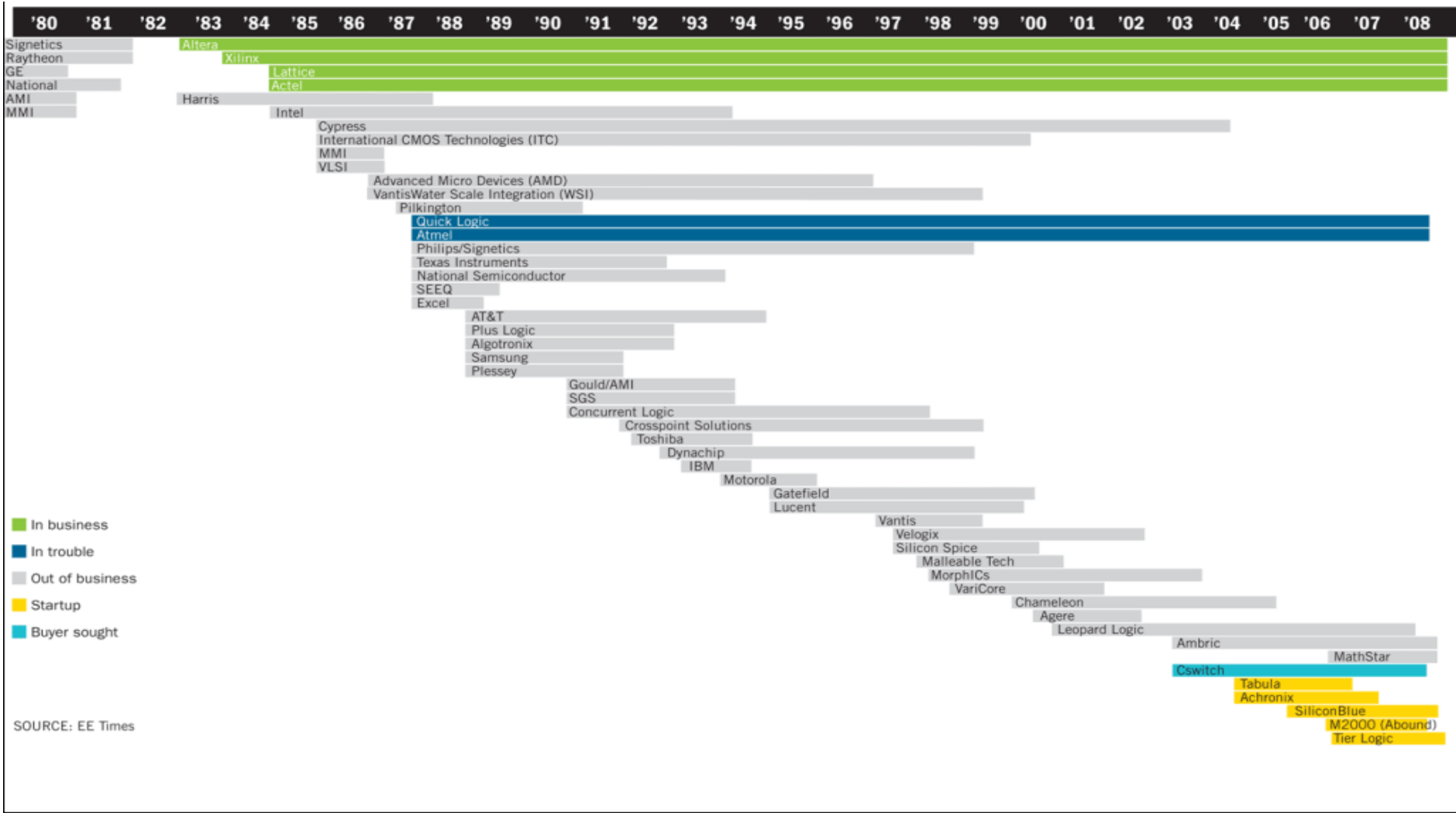
2015年12月

Capital Microelectronics

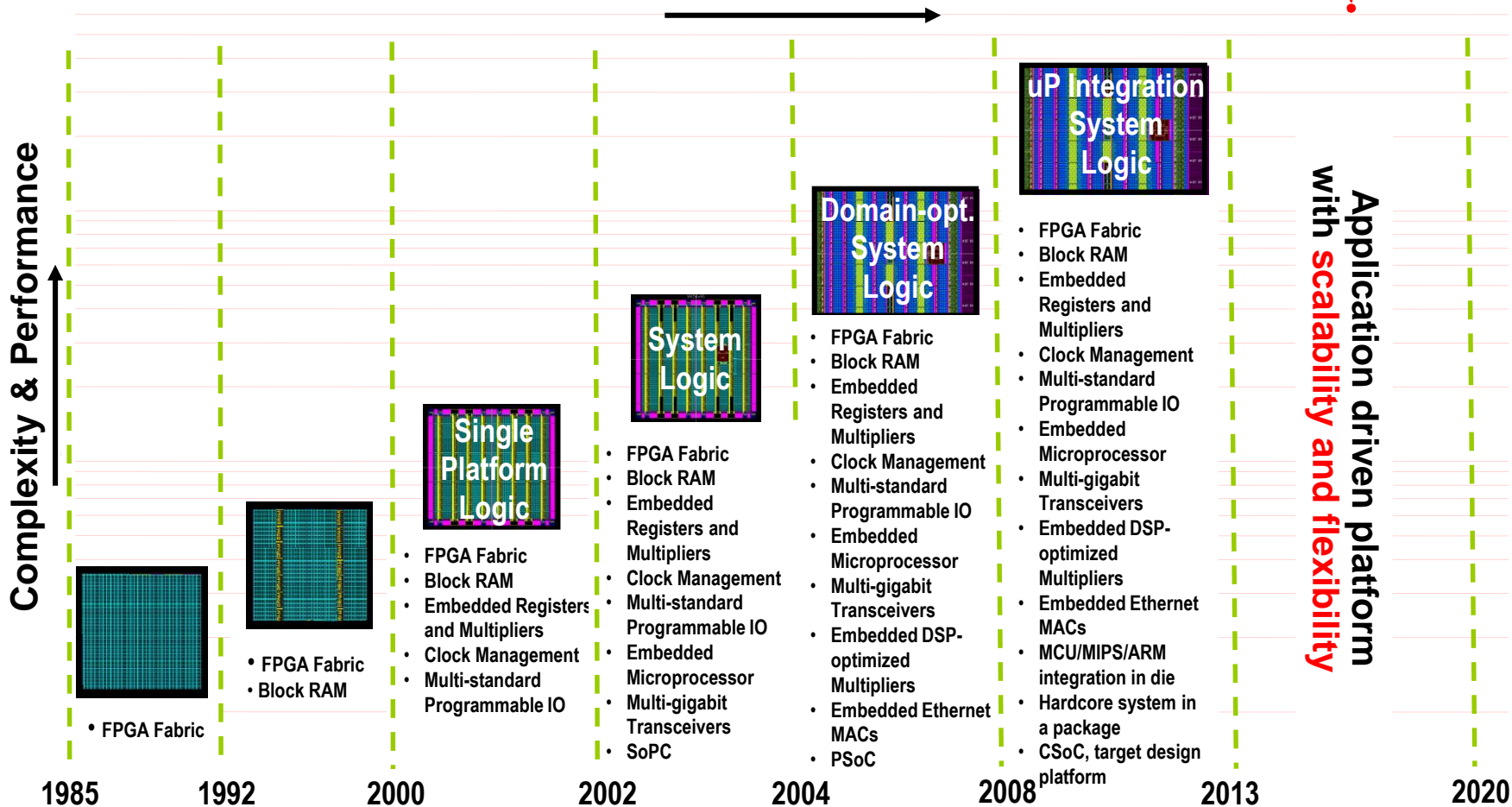
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- ◆ 重温过去
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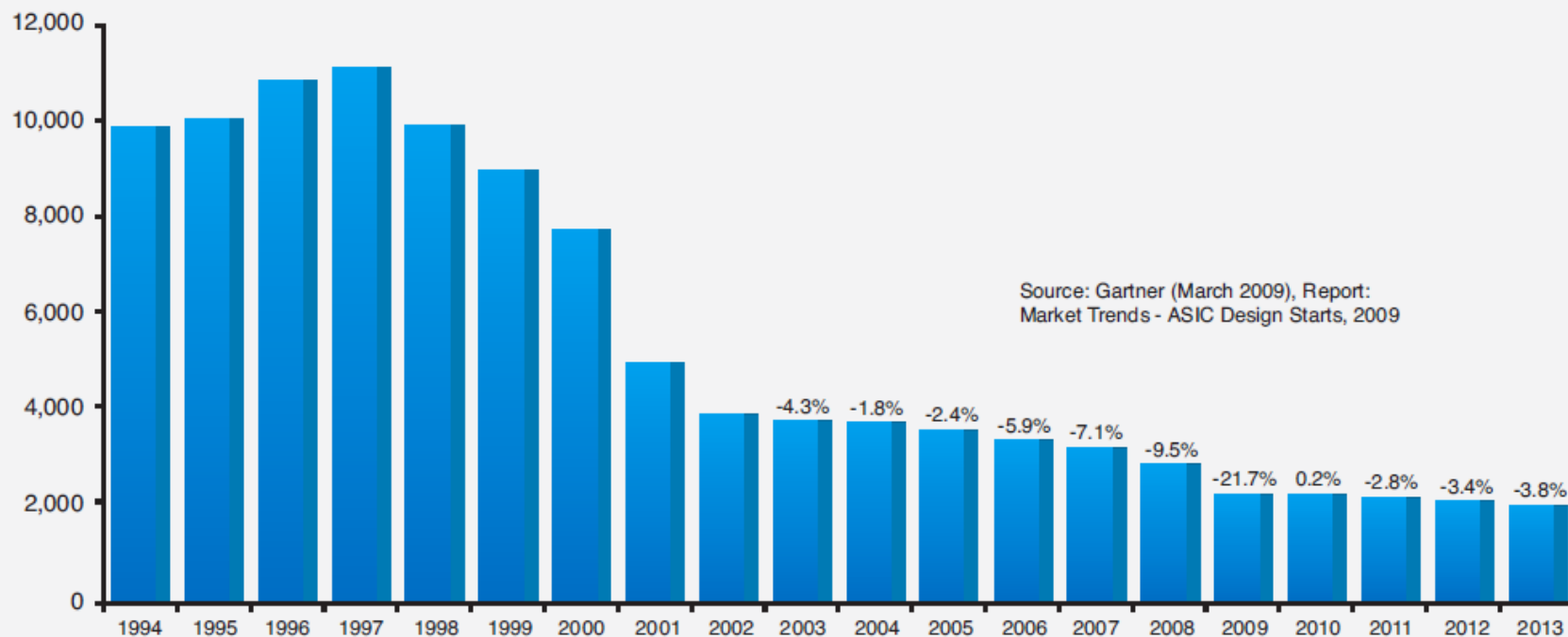




Scalability & Flexibility

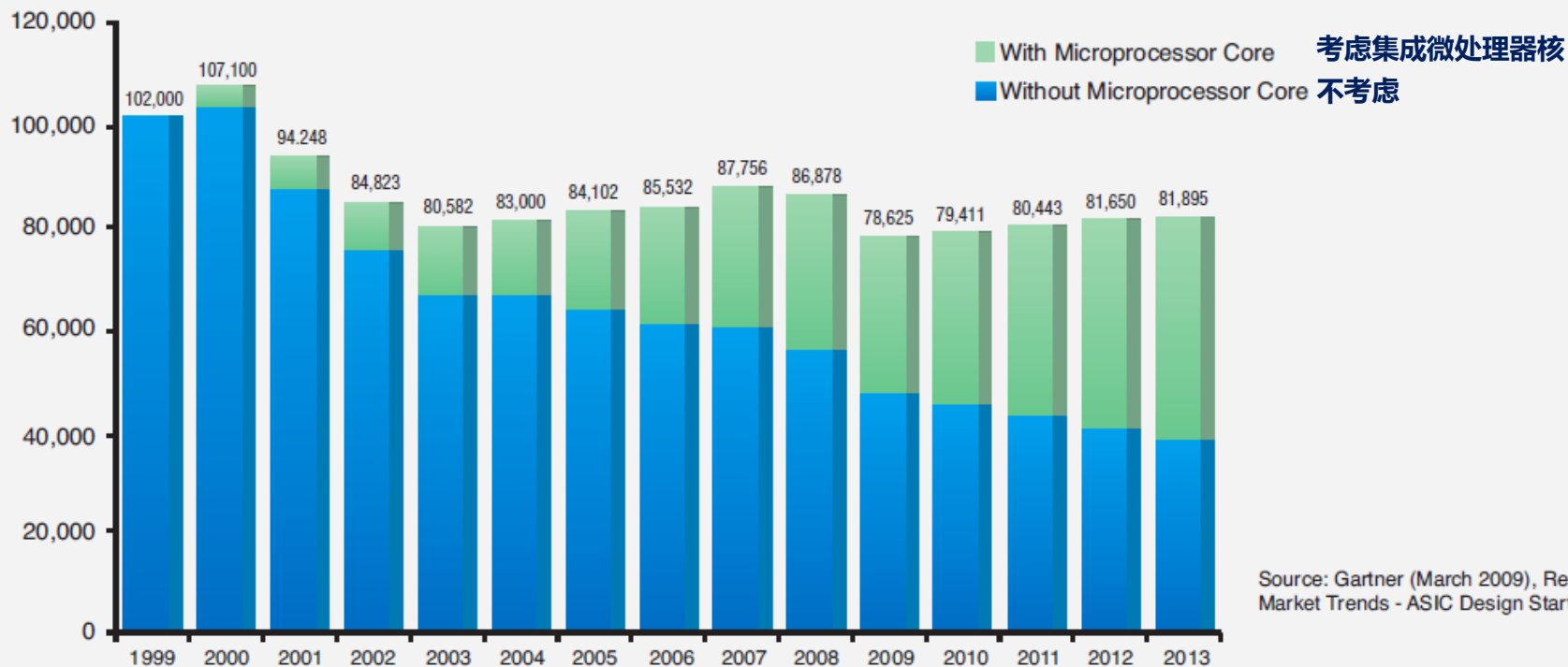


Estimated Worldwide ASIC Design Starts, 1994-2013 全球ASIC设计开始数量统计：1994-2013



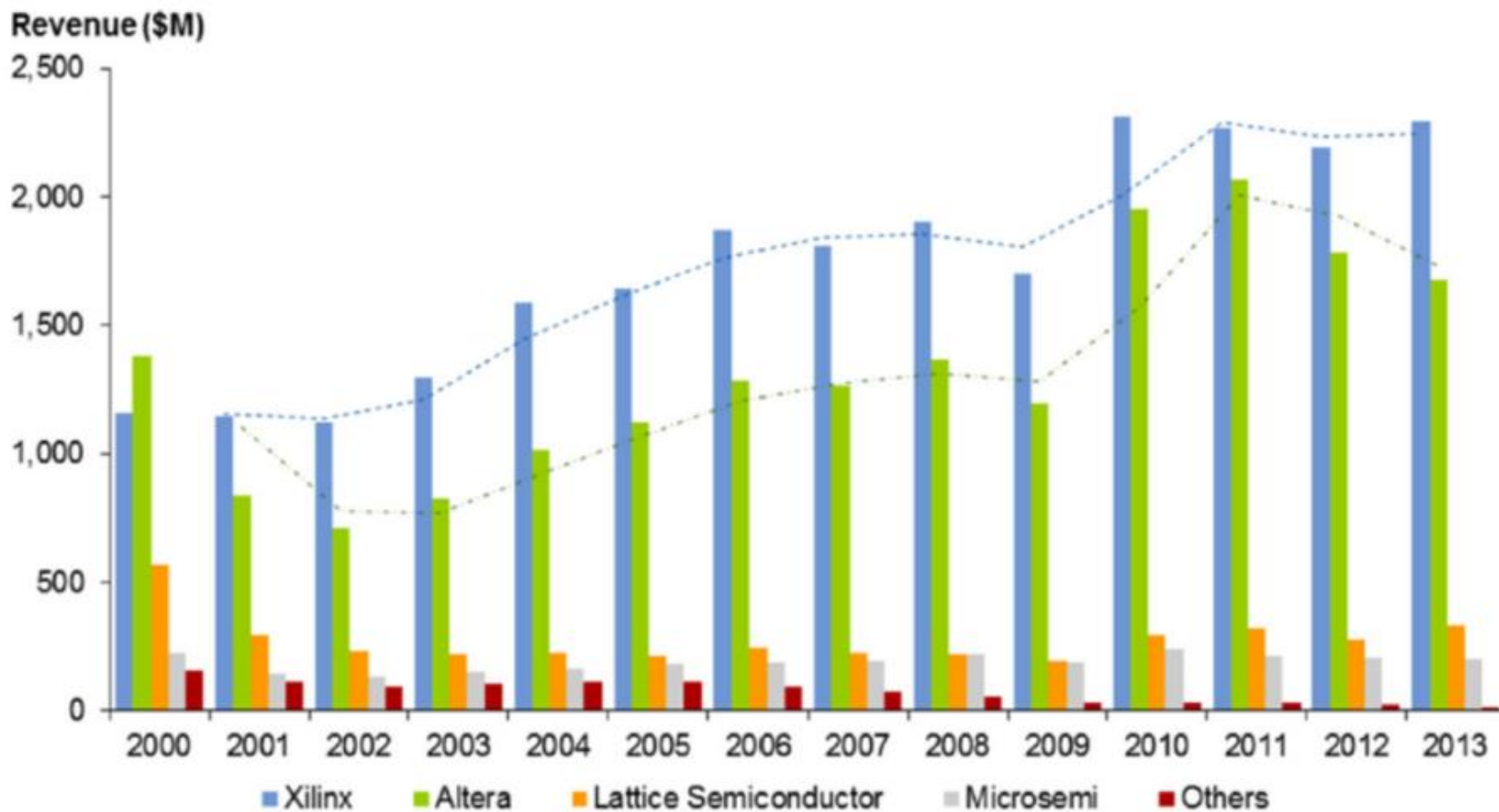
Estimated FPGA /PLD Design Starts, 2003-2013

全球FPGA/PLD设计开始数量统计：1999-2013



Source: Gartner (March 2009), Report: Market Trends - ASIC Design Starts, 2009

FPGA Vendors' Revenue, 2000 to 2013



FPGA = field-programmable gate array

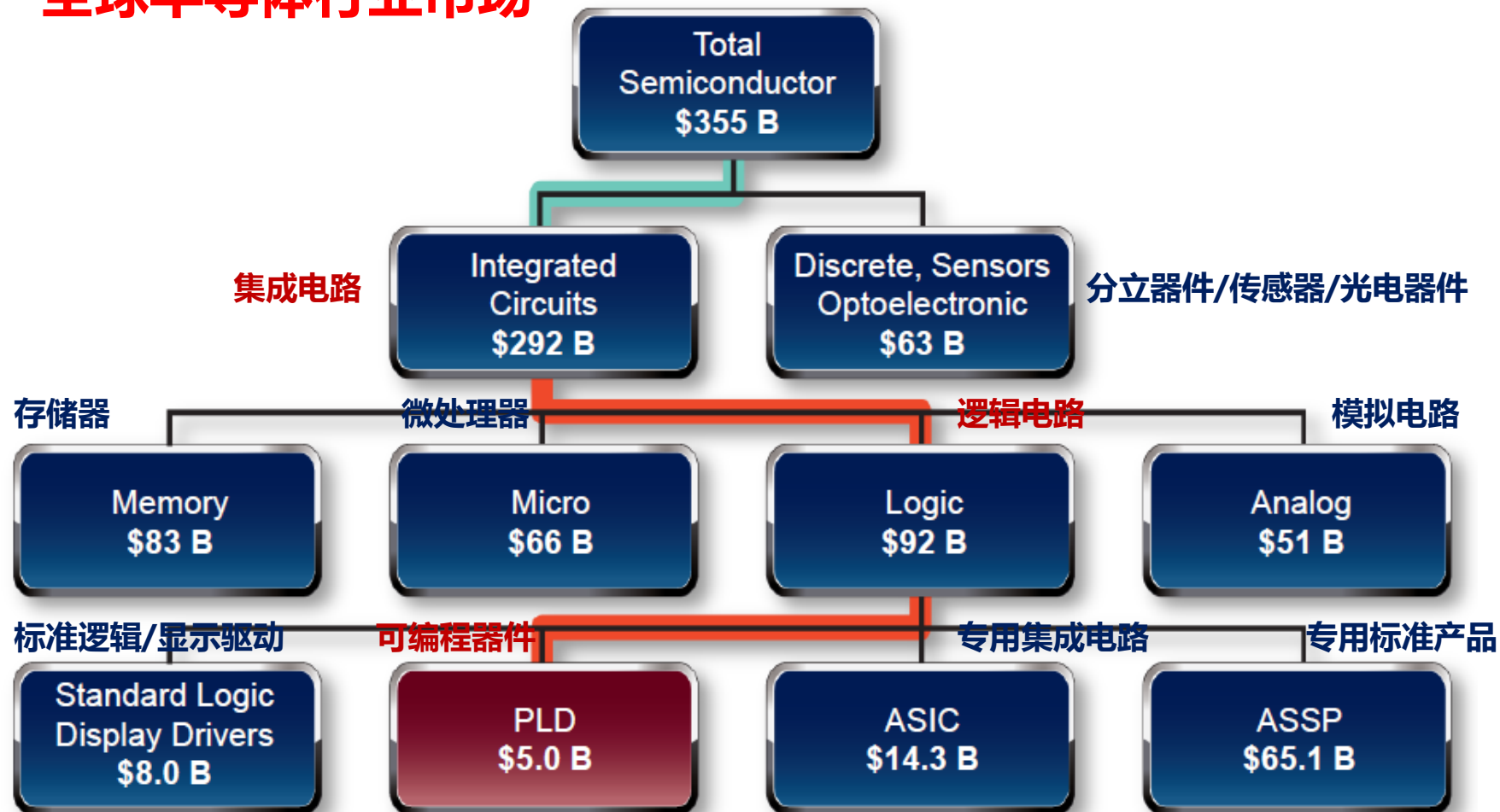
Source: Gartner (October 2014)

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Worldwide Semiconductor Market - 2014

全球半导体行业市场



FPGA : 可编程逻辑门阵列85%
CPLD : 复杂可编程逻辑器件15%

Source: IHS iSuppli

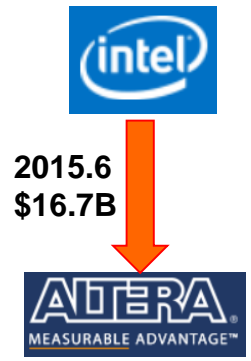
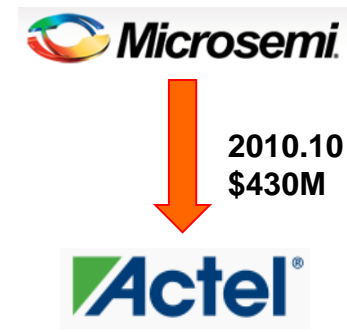
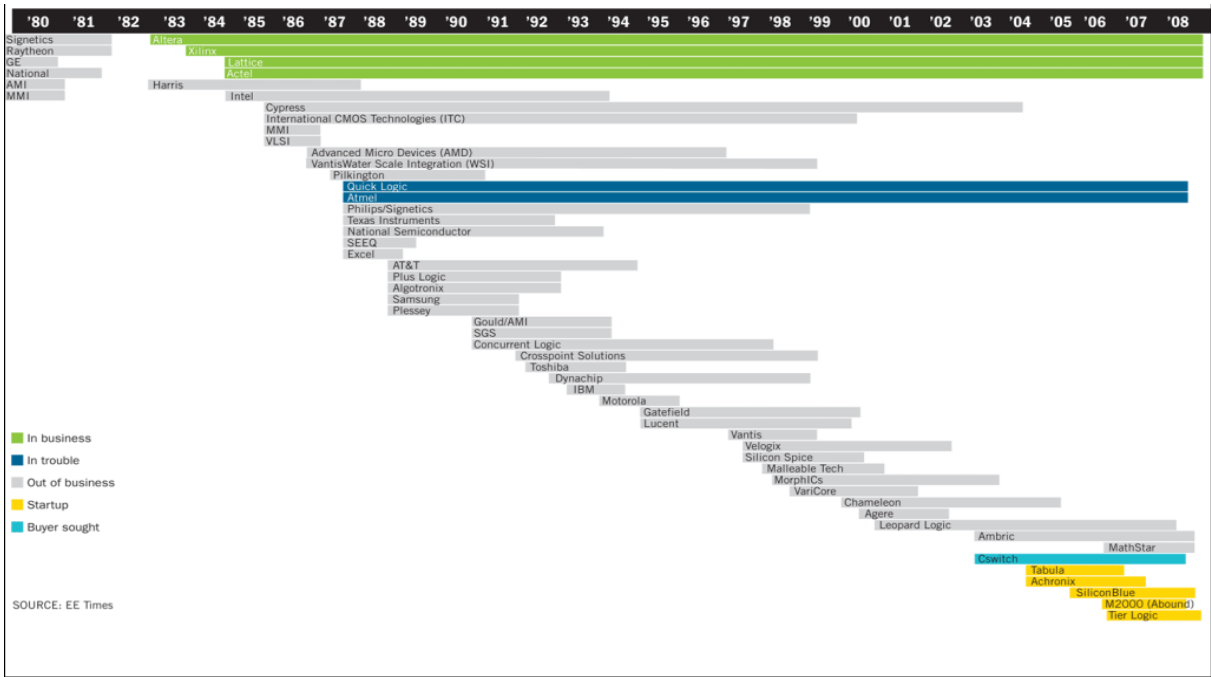
Key Attributes of FPGA, ASSP and ASIC Chips From the Equipment Perspective

Attributes	FPGA	ASSP	ASIC		
Ability to Customize					
Fast Time-to-Market					
Mask/Yield/Design and Tool Costs					
Low Risk					
Suitable for Emerging Standards					
Suitable for High-Volume*					
Suitable for Highest Performance Designs					
Low Cost Per Chip					
	Poor	Challenge	Average	Good	Excellent

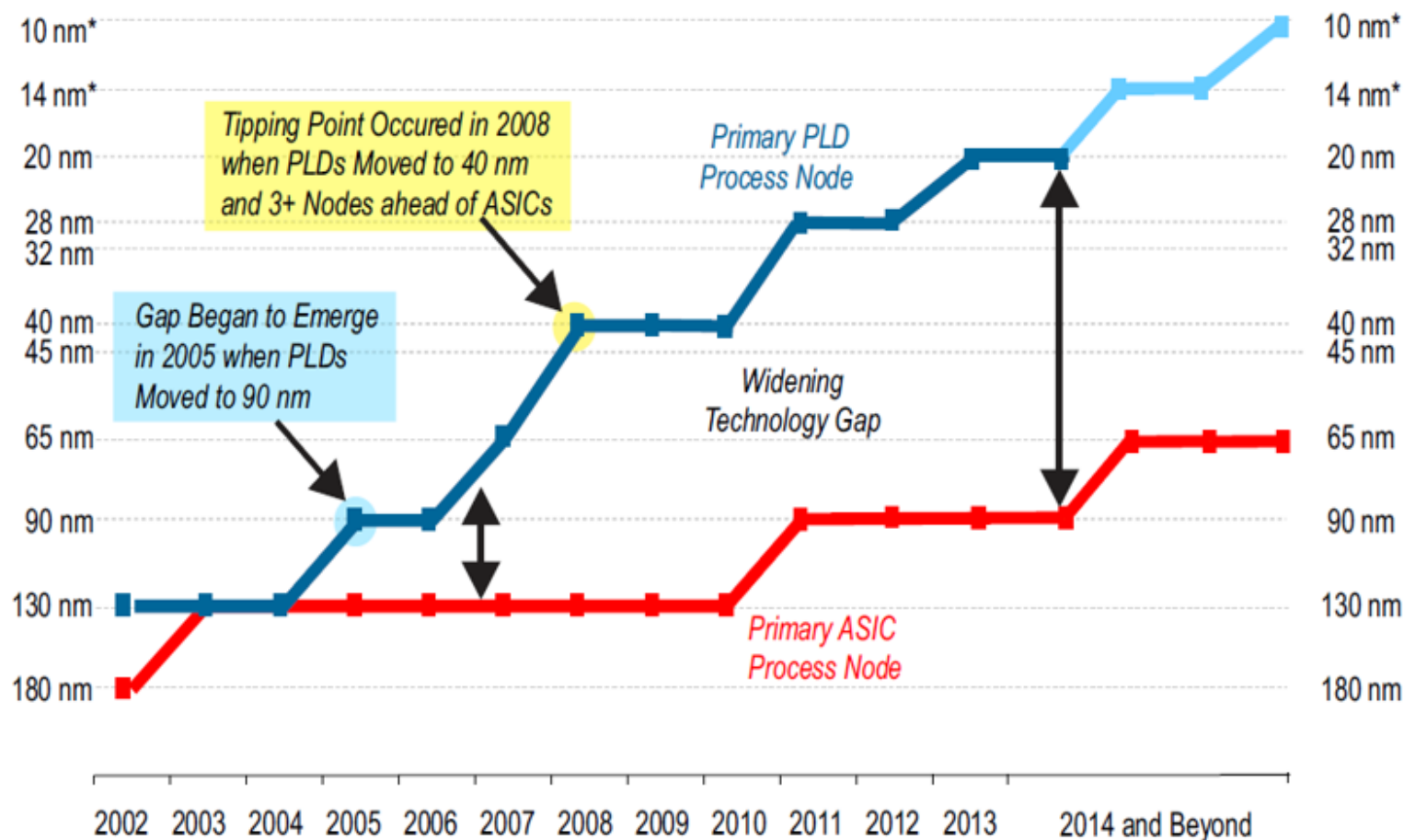
Note: *There are cases when lower-end FPGA/PLDs can meet high-volume cost requirements.

ASIC = application-specific integrated circuit; ASSP = application-specific standard product; FPGA = field-programmable gate array; PLD = programmable logic device

Source: Gartner (October 2014)

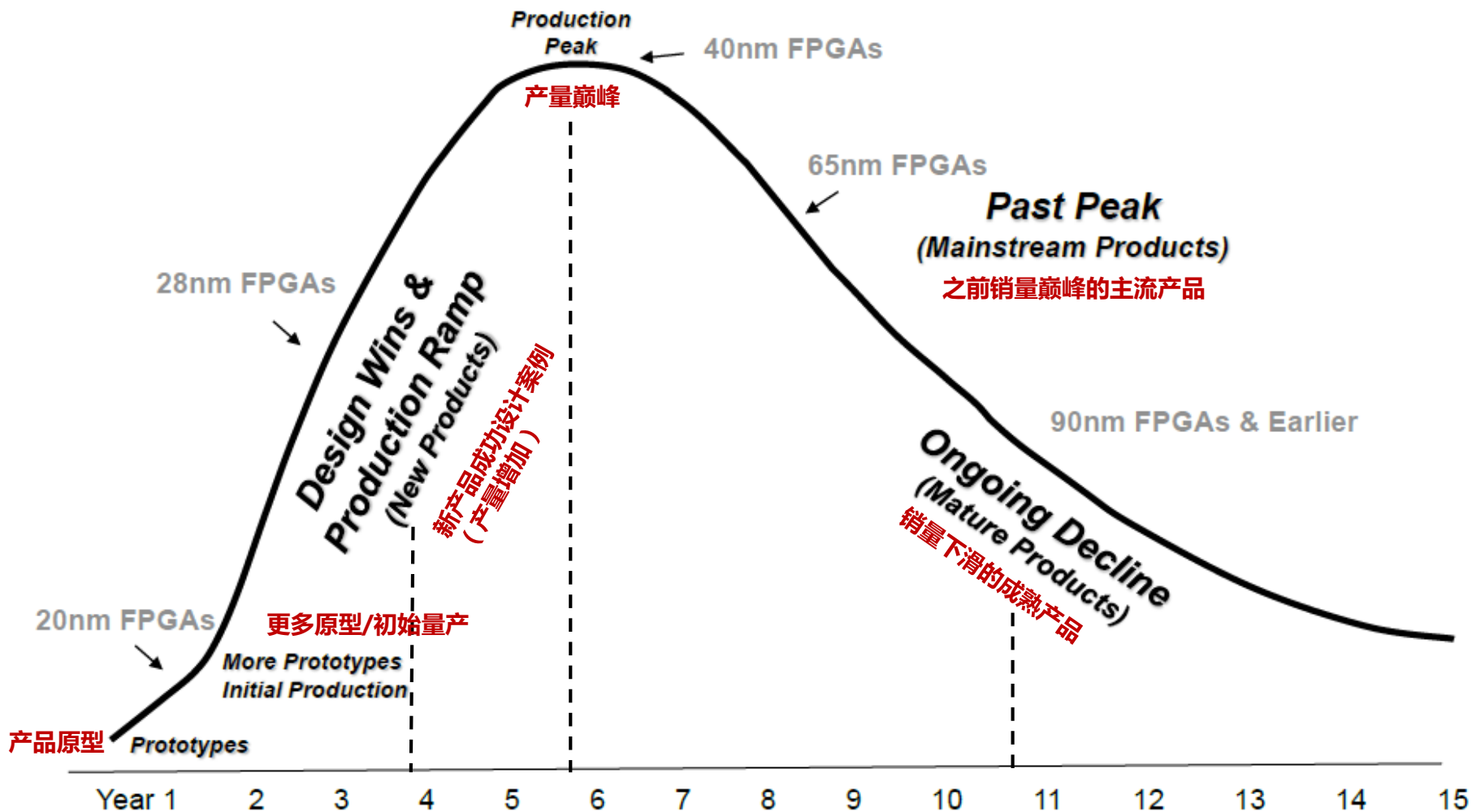


Programmable Logic vs. ASIC Primary Process Nodes for New Designs



Source: Altera; Data applies to new design starts.

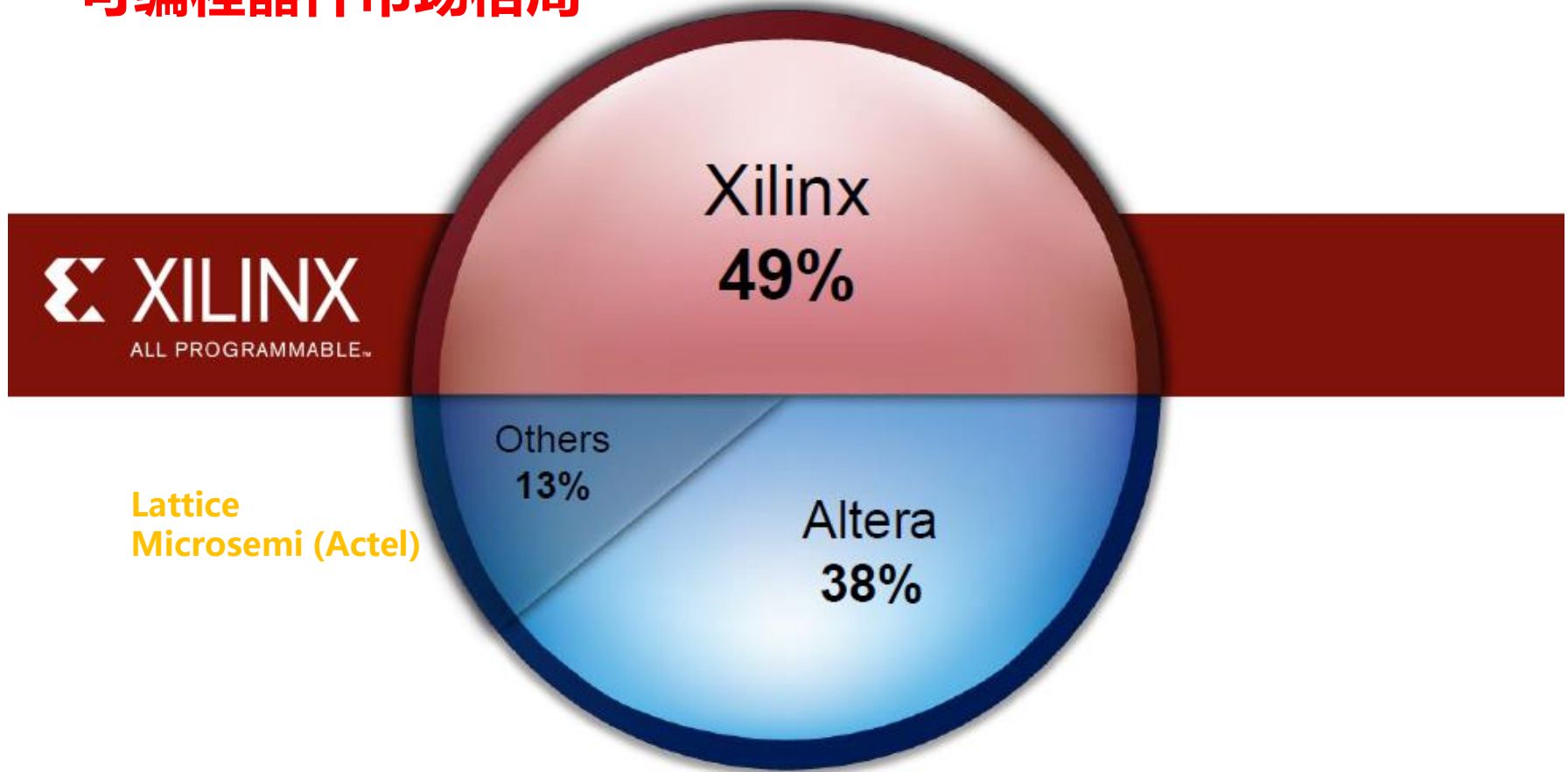
* FinFET Technology. Timeframe for PLDs on 14 nm and 10 nm FinFET technology to be announced.



Source: Altera; based on historical revenue ramps of products in the PLD industry

PLD Market Share - Calendar Year 2014

可编程器件市场格局

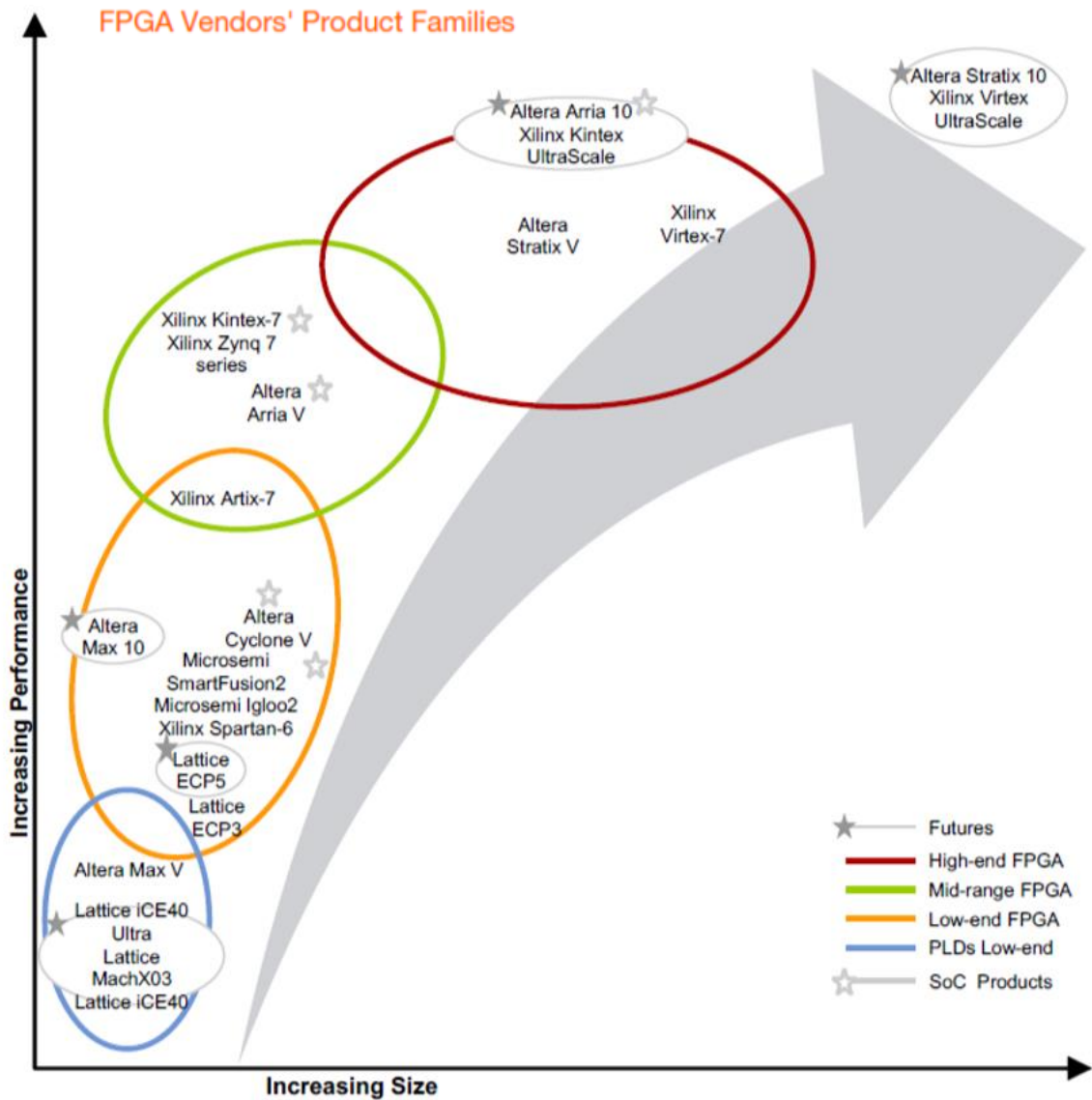


Lattice
Microsemi (Actel)

With nearly 50% Market Share, Xilinx is the #1 PLD Supplier

Xilinx仍然是世界上最大的可编程逻辑器件供应商，2014年市场占有率将近50%

Source: IHS iSuppli



FPGA = field-programmable gate array; PLD = programmable logic device; SoC = system-on-chip

Source: Gartner (October 2014)

Segments of the Programmable Market

Segment	Characteristics	Applications	Vendor Offerings
High-end FPGA category (ranges from 200K to 2,000K LCs).	Performance and size are the most important considerations. These devices favor high-complexity, lower volume and larger designs that are not power- or cost-sensitive.	At this end of the market, providers favor use cases and applications in which customization is important — but for which ASICs are either too expensive, risky or time-consuming to be used effectively. Key applications are in the wired communications, industrial and military sectors.	Xilinx and Altera are both pushing the latest node. Both companies compete directly with their Virtex and Stratix products, respectively.
Midrange FPGA category (ranges from 25K to 505K LCs).	The midrange of the market focuses on designs that are slightly smaller and lower-cost, but where good to excellent performance is still required.	Examples of applications in this segment include base stations, surveillance systems and solid-state drives.	Most competition in this space is between Altera and Xilinx. New devices that have been announced and which are in early-phase production include Altera's Arria 10 and Xilinx's Kintex UltraScale.
Low-end FPGA category (2K to 301K LCs).	The low end of the FPGA market typically suits requirements for larger "glue logic," and sometimes incorporates higher-level blocks of logic.	Applications in aerospace and military systems with strong environmental requirements; and in communications and industrial systems where reliability, security and persistence are desirable.	All four vendors (namely Altera, Lattice Semiconductor, Microsemi and Xilinx) have offerings in this category. Microsemi's non-volatile, mostly Flash-based offerings favor most applications.
PLD category (up to 30K macrocells or LCs).	Dominated by lower-power, lower-cost and higher-volume applications, or "glue logic."	Particularly suited to cost-sensitive and low-power applications that require interface and bridging, sensor fusion, basic "glue logic" and other companion chip functionality. They are also usable in many low-power IoT applications.	All four vendors compete here, although Lattice Semiconductor has carved out a niche for itself at the very low end with its ICE family of parts. These are designed into several Samsung Electronics smartphones. Microsemi targets military applications such as drones and surveillance systems.

ASIC = application-specific integrated circuit; FPGA = field-programmable gate array; IoT = Internet of Things; K = thousands; LC = logic cell; PLD = programmable logic device

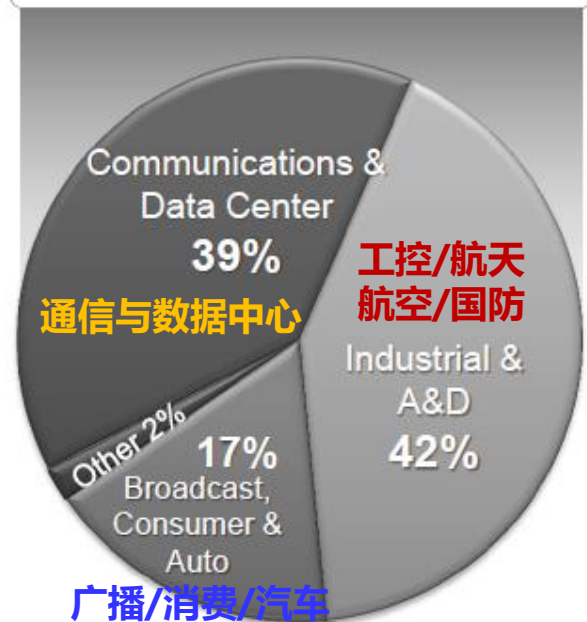
Source: Gartner (October 2014)

Revenue Breakdown - March Quarter 2015

Xilinx收入分解 - 2015年第一季度



Revenue by End Market



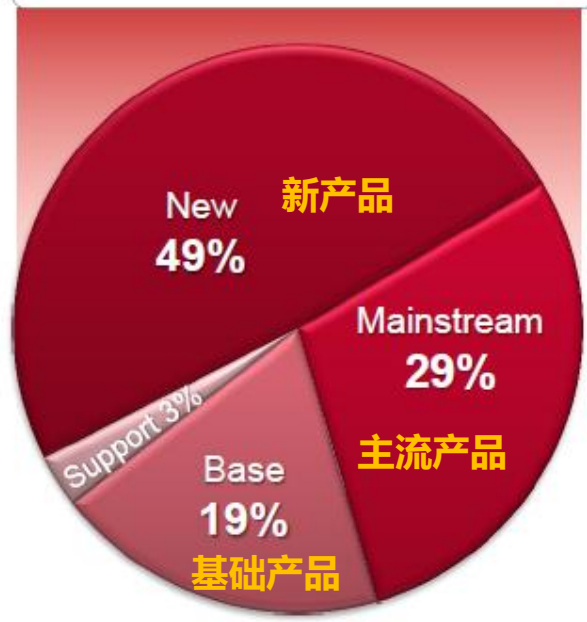
按终端市场分类

Revenue by Geography



按地域分类

Revenue by Category



按产品分类

Serving a Wide Range of Markets

Xilinx产品服务广泛的市场



Aerospace and Defense

- > Avionics, MILCOM
- > Space

航空航天与国防

Communications

- > Wired and wireless networking
- > Data center

通信



Industrial, Scientific, Medical

- > Ultrasound systems
- > Motor controllers

工控/科学/医疗

Audio, Video, Broadcast

- > 3D cameras
- > Video transport

声音/视频/广播



Automotive

- > Infotainment
- > Driver assistance

汽车电子

Consumer

- > Multi-function printers
- > eReaders

消费电子

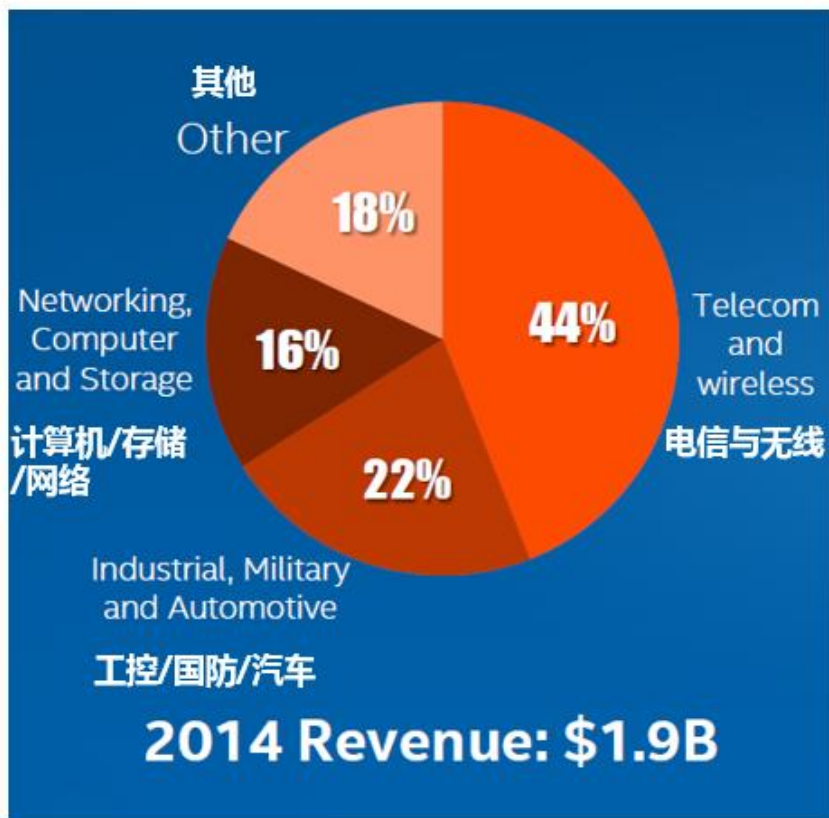


Test & Measurement

- > Communications instruments
- > Semiconductor ATE

测试与仪器

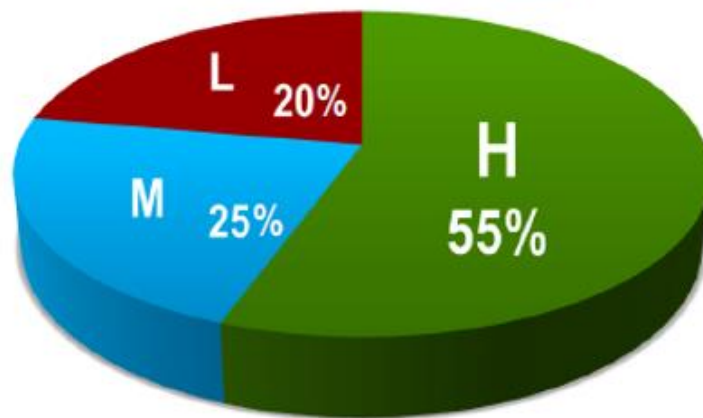
Sizing the Markets, Sizing the Products



Total FPGA Revenue By FPGA Class Projected for 28nm, 20nm, 14nm

H = High end M = Mid-range L = Low end

H 高端 ; M 中端 ; L 低端



Diverse markets served by a portfolio of FPGAs

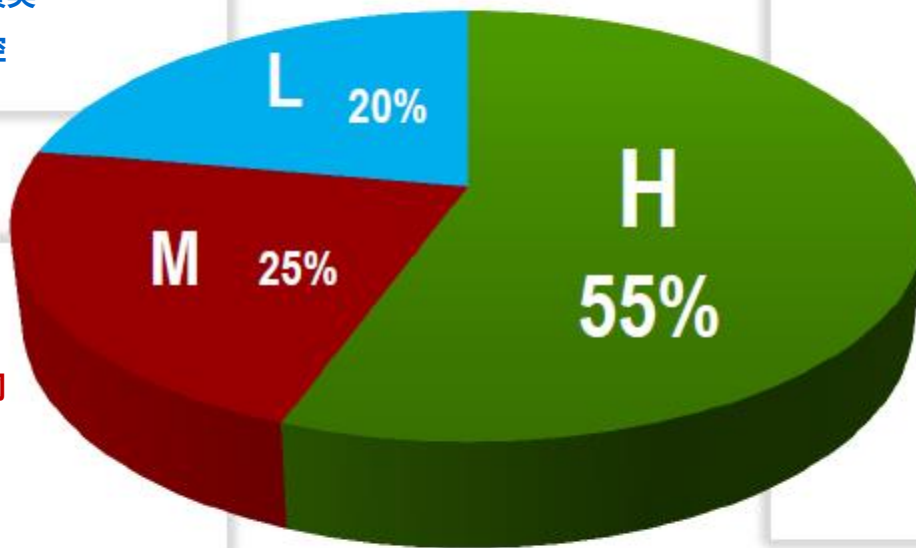
The Displacement Opportunity

Altera产品取代其他产品的机会

- Automotive 汽车电子
- Consumer 消费类
- Industrial 工控

- Broadcast 广播
- Networking (enterprise) 网络企业网
- Wireless (radio) 无线电台

H高端 ; M中端 ; L低端



- Computer & Storage 计算机/存储
- Medical 医疗
- Military 国防
- Networking (service provider) 网络
- Telecom 电信
- Test & Measurement 测试/仪器
- Wireless (baseband & radio) 无线

被取代的产品种类



Products to be displaced



COMPELLING MARKET OPPORTUNITIES

Increasing Complexity & Connectivity



Lattice产品为创新应用提供机会

GROWING APPLICATIONS



消费

CONSUMER

Internet of Things (IoT),
Smartphones, Tablets,
Wearables, Smart TV

物联网/智能手机/平板/可穿戴/智能电视



工控

INDUSTRIAL

Surveillance, Human-
Machine Interface
(HMI), Automation

智能监控/人机接口/自动化



通信

COMMUNICATIONS

Small Cells, Backhaul,
Wired Access,
Aggregation

小基站/传输网络/有线接入/汇聚网

DRIVERS & NEEDS

Mobile Revolution

- Connecting everything
- Rapidly decreasing price points
- Low power

无缝连接/成本敏感/低功耗

Industrial Evolution

- Sensor proliferation
- Improved machine vision analytics
- Virtual reality

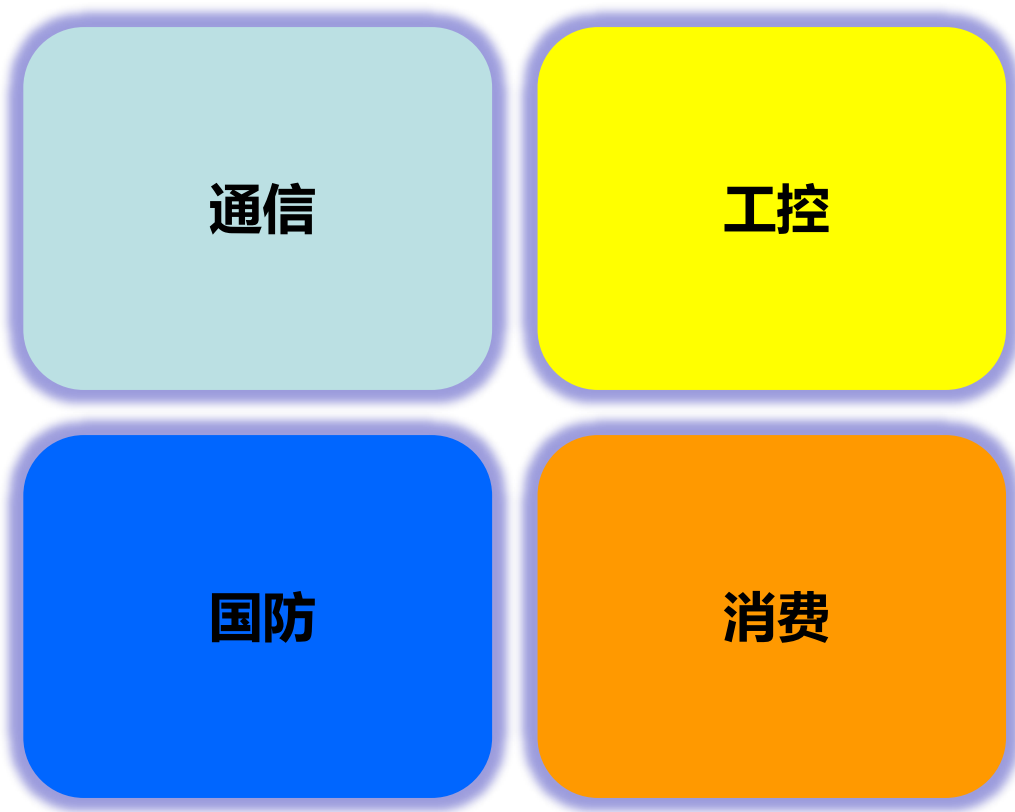
集成传感器/提高机器视觉分析/虚拟现实

Infrastructure Loading

- Mobile data traffic increase
- Rapid transition to cloud-based infrastructure

移动数据业务增长/转移到云计算架构

逻辑规模较大
性能可靠性要求高



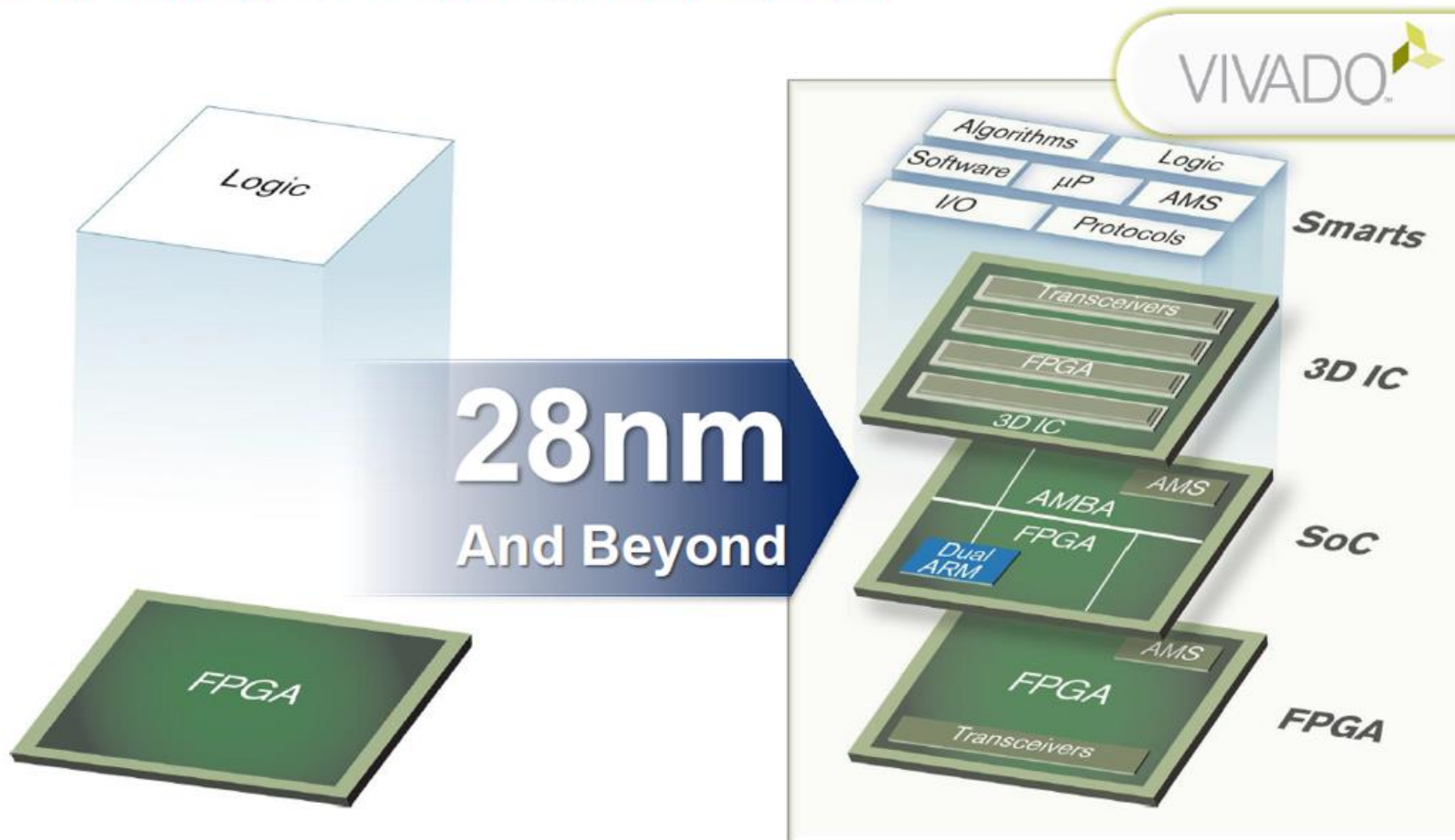
逻辑规模较小
成本敏感
功耗小

四大主战场

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Delivering A Generation Ahead



Programmable Logic Devices
Enables Programmable Logic



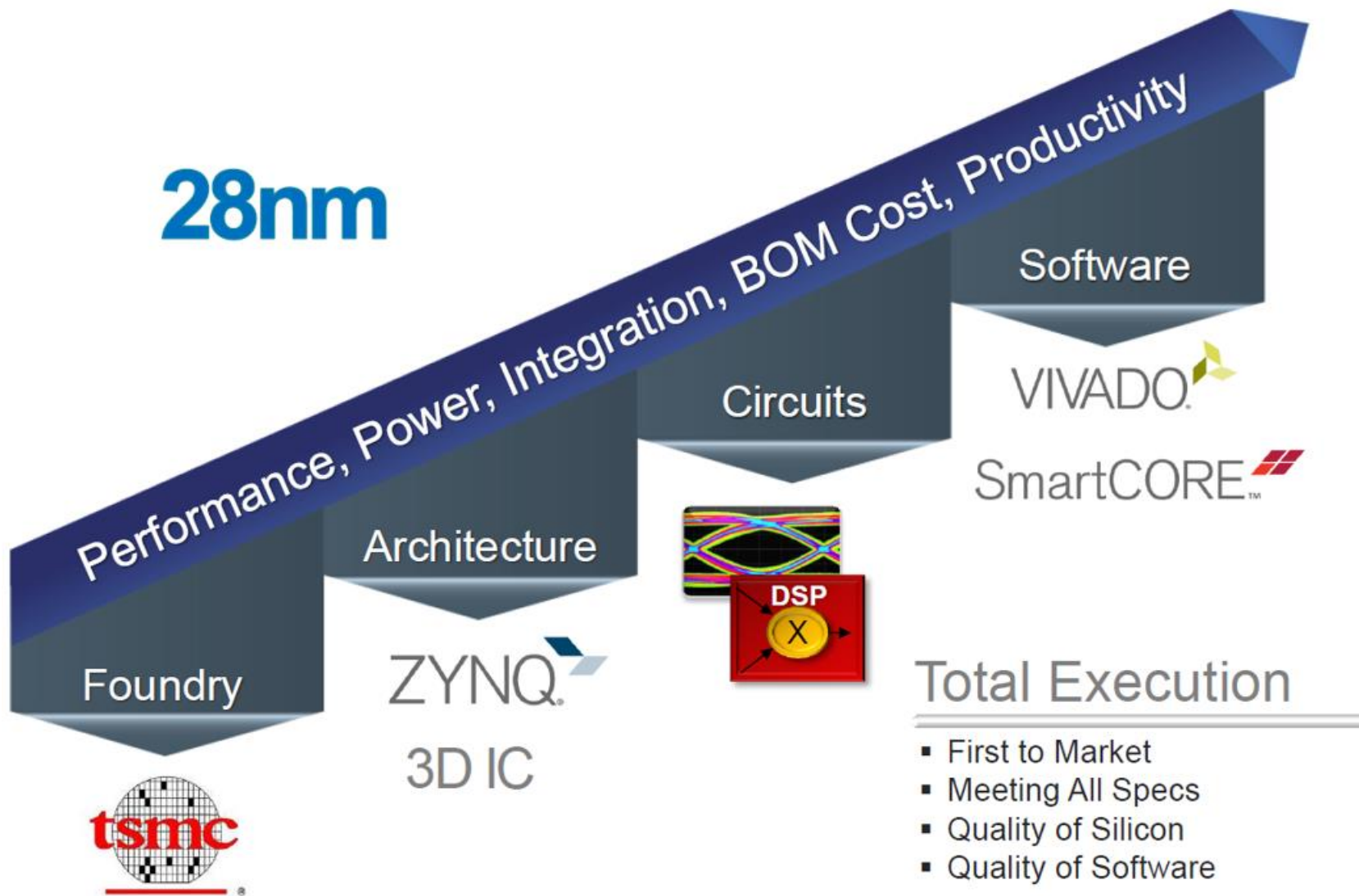
All Programmable Devices
Enables All Programmable & Smarter Systems

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XILINX ALL PROGRAMMABLE.

Proven Formula: 5 Strategic Advantages at 28nm

28nm

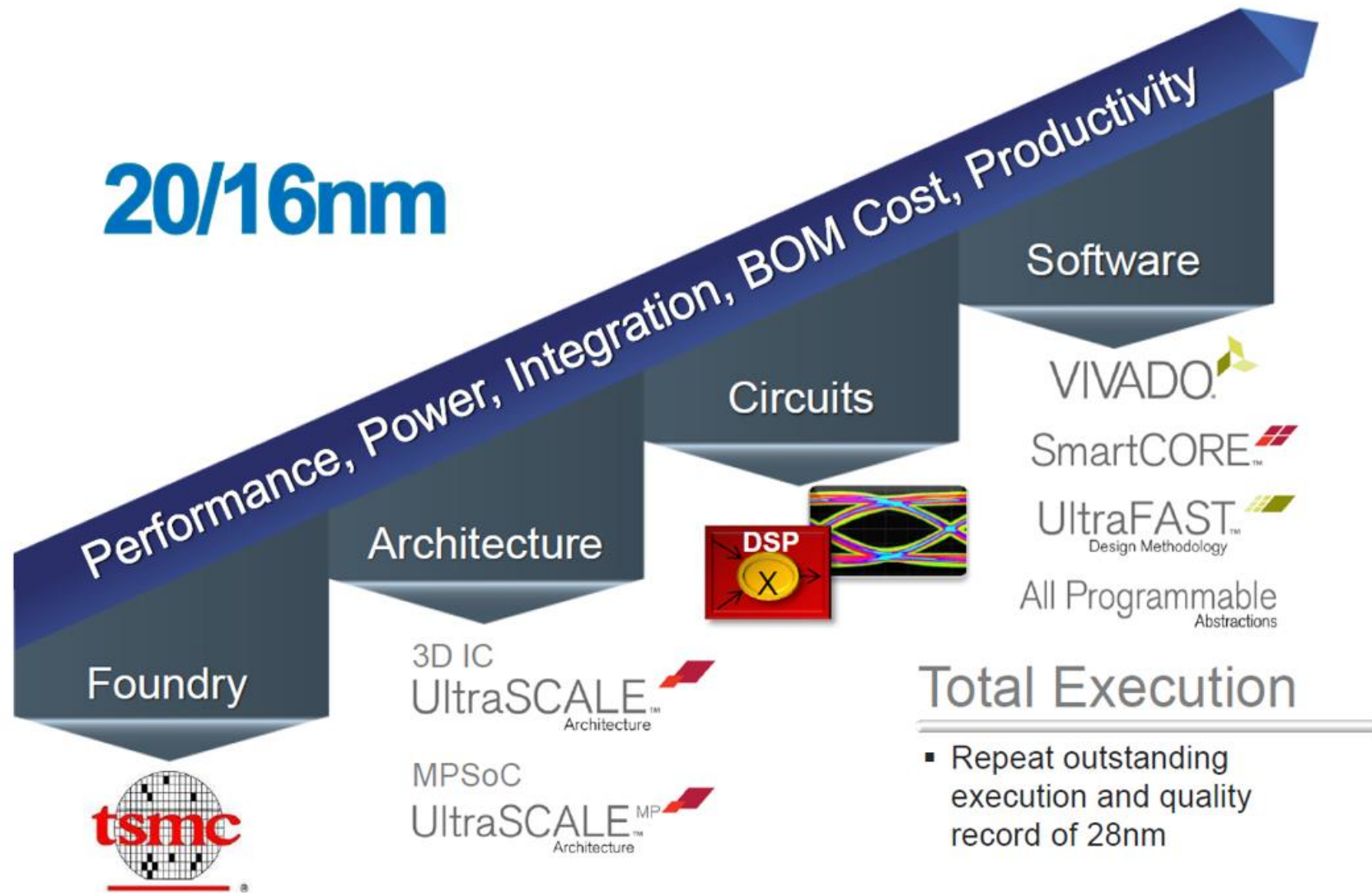


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XILINX ALL PROGRAMMABLE

Proven Formula: 5 Advantages for 20/16nm

20/16nm



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XILINX ALL PROGRAMMABLE.

Proven Formula for Share Gains

Strategic Advantages

5

ADVANTAGES

- Foundry
- Architecture
- Circuits
- Total Execution
- Software

Driving Consecutive Share Gains



FY2012

FY2013

FY2014

FY2015

FY2016

FY2017

FY2018

FY2019

FY2020

FY2021...

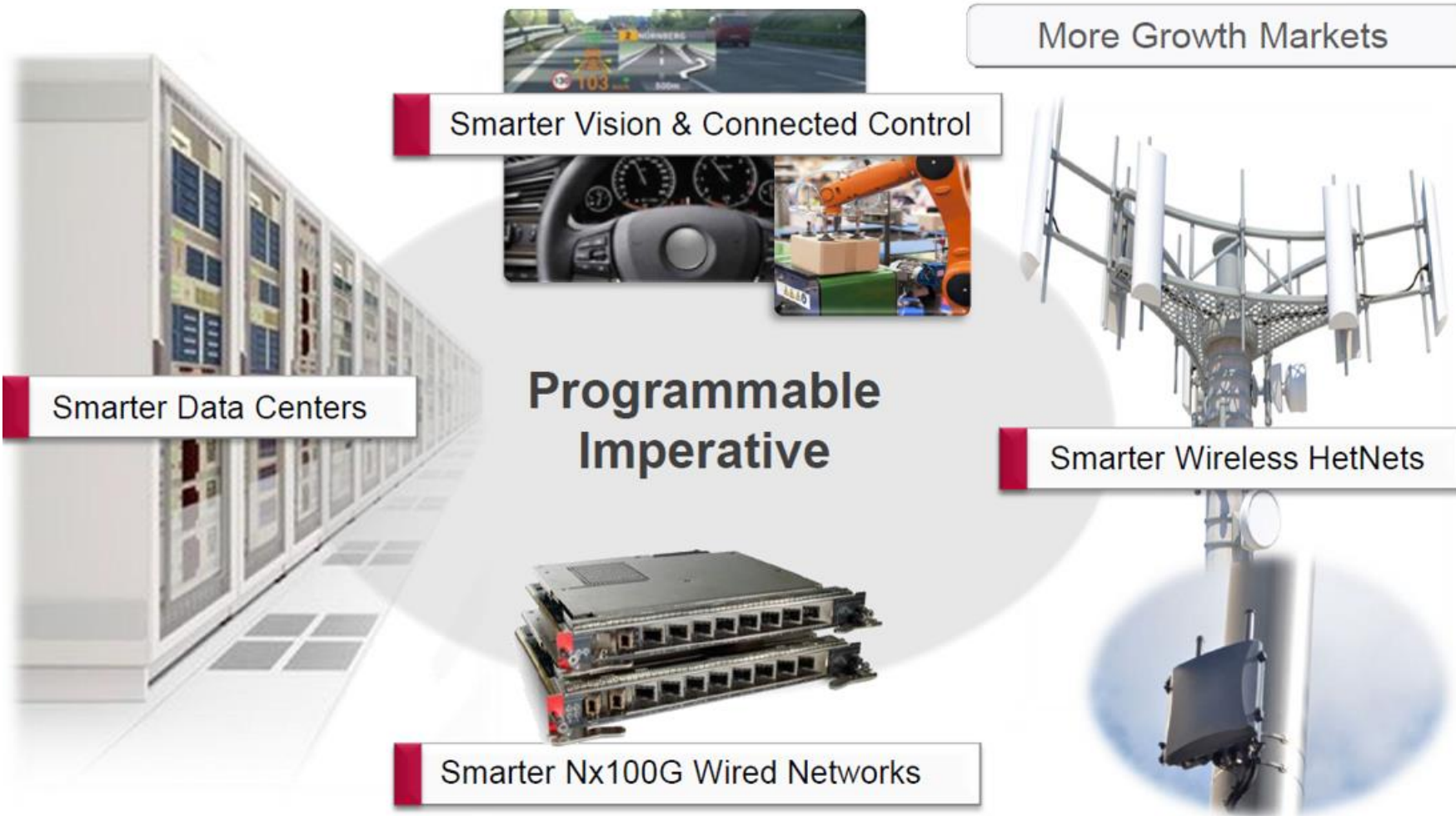
28nm ▶

20/16nm ▶

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XILINX ALL PROGRAMMABLE.

Focus on Industry Growth Megatrends



More Growth Markets

Smarter Vision & Connected Control

Smarter Data Centers

**Programmable
Imperative**

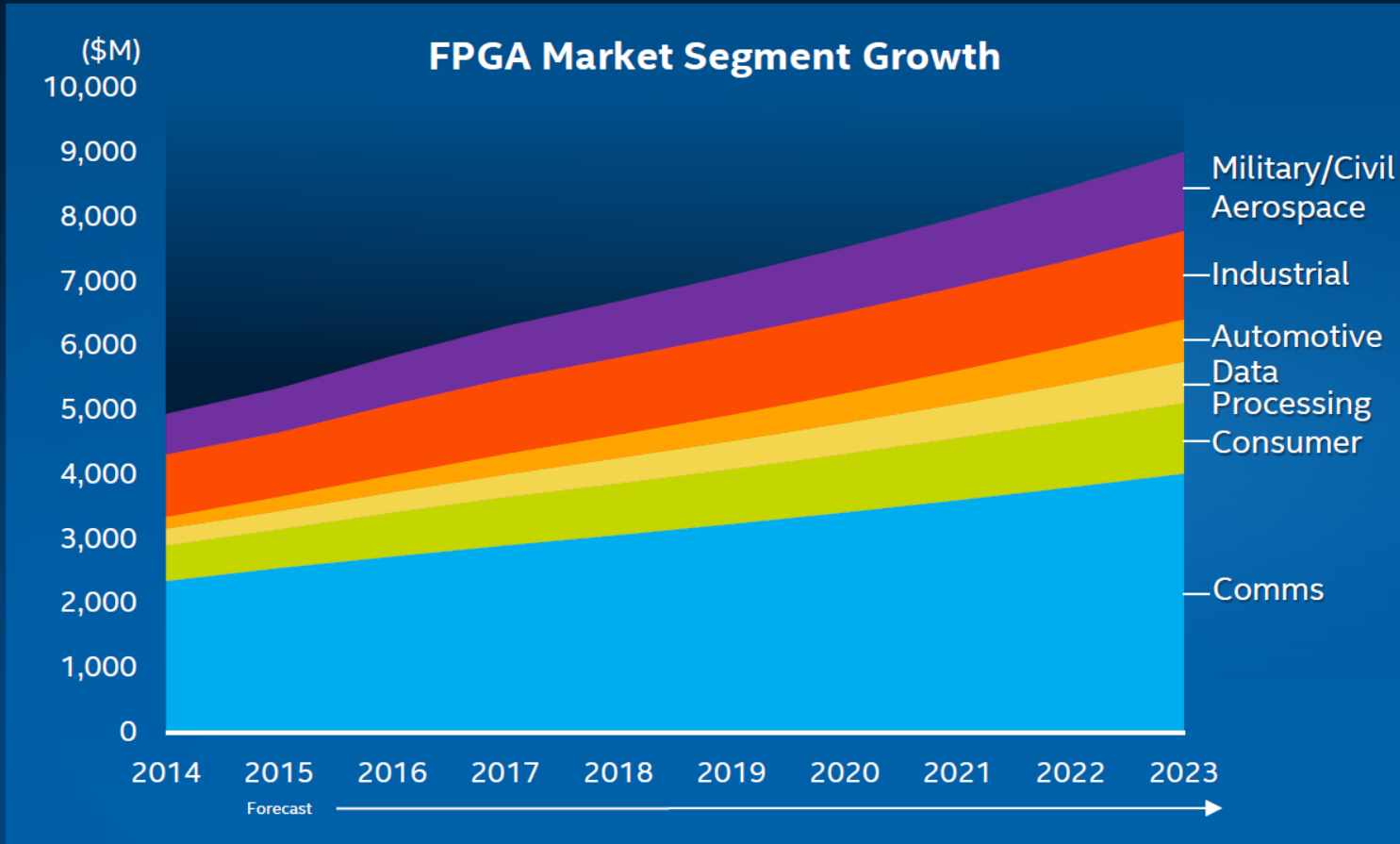
Smarter Wireless HetNets

Smarter Nx100G Wired Networks

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XILINX > ALL PROGRAMMABLE.

...In a Growing Market Segment

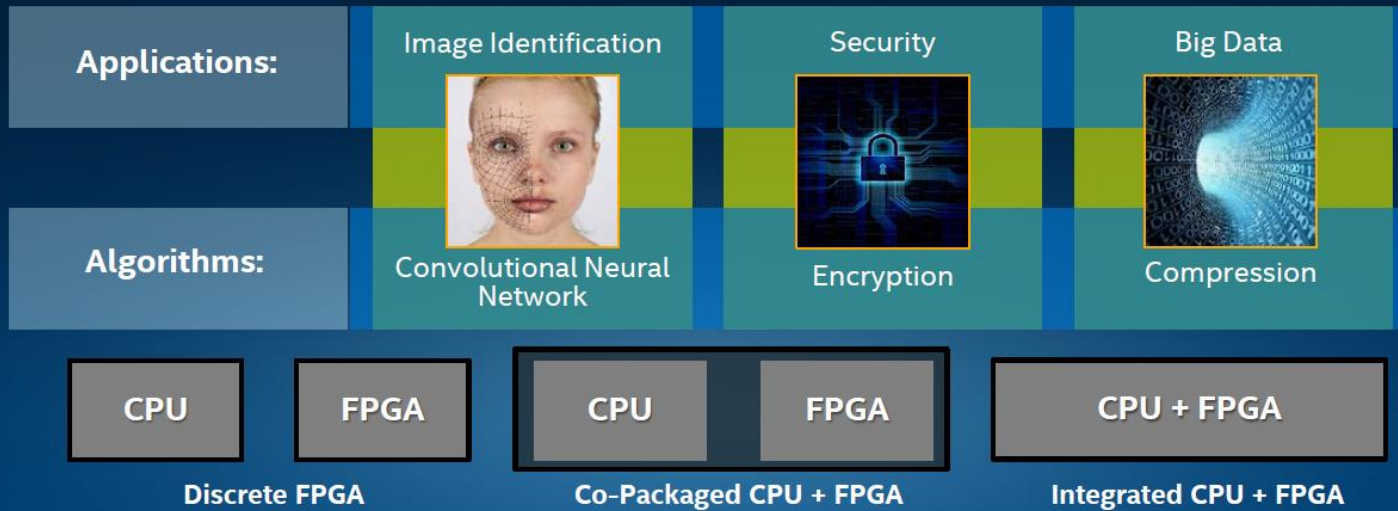


CAGR
7%

Source: Gartner

Cloud Example: Data Center FPGA Acceleration

Up to 1/3 of Cloud Service Provider Nodes to Use FPGAs by 2020



Today 

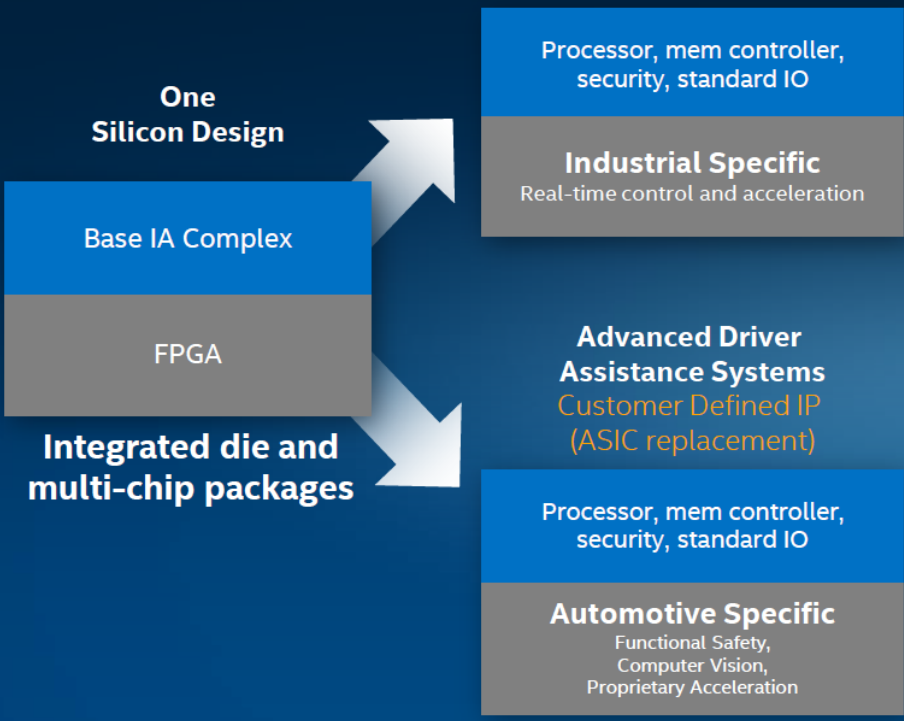
>2X performance increase through integration

Reduces total cost of ownership (TCO) by using standard server infrastructure

Increases flexibility by allowing for rapid implementation of customer IP and algorithms

<https://gigaom.com/2015/02/23/microsoft-is-building-fast-low-power-neural-networks-with-fpgas/>

IoT Application Examples



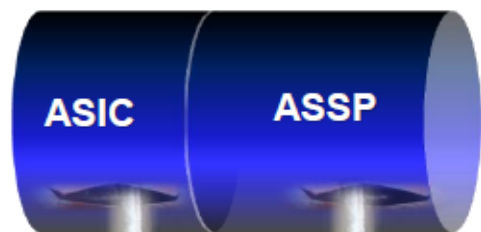
- **Integrated solutions accelerate growth in key IoT segments by adding new functionality, improving performance, and lowering cost**
- **~\$11B incremental SAM by 2020 as integrated FPGAs become cost competitive with ASICs & ASSPs**
- **Customers can program their own IP, replacing ASICs**
- **Intel can pre-program industry-specific IP, replacing ASSPs**
- **Expected to reduce time-to-market by more than 50%**

预计2022至2032年所有SOC系统
芯片将全部具有可编程功能

Y14: 5B -> Y16: 16B
年复增长率CAGR: ~79%

2016年市场容量

2016E Available



预估到2016年
市场容量突破
160亿美元

2016E Serviceable

> \$16B SAM

Xilinx

\$2B
SAM

Embedded

ALL
Programmable
SAM
全编程部分

\$8B
SAM

ASIC/ASSP
Displacement

Evolutionary
FPGA
SAM
演进部分

\$6B
SAM

Core PLD

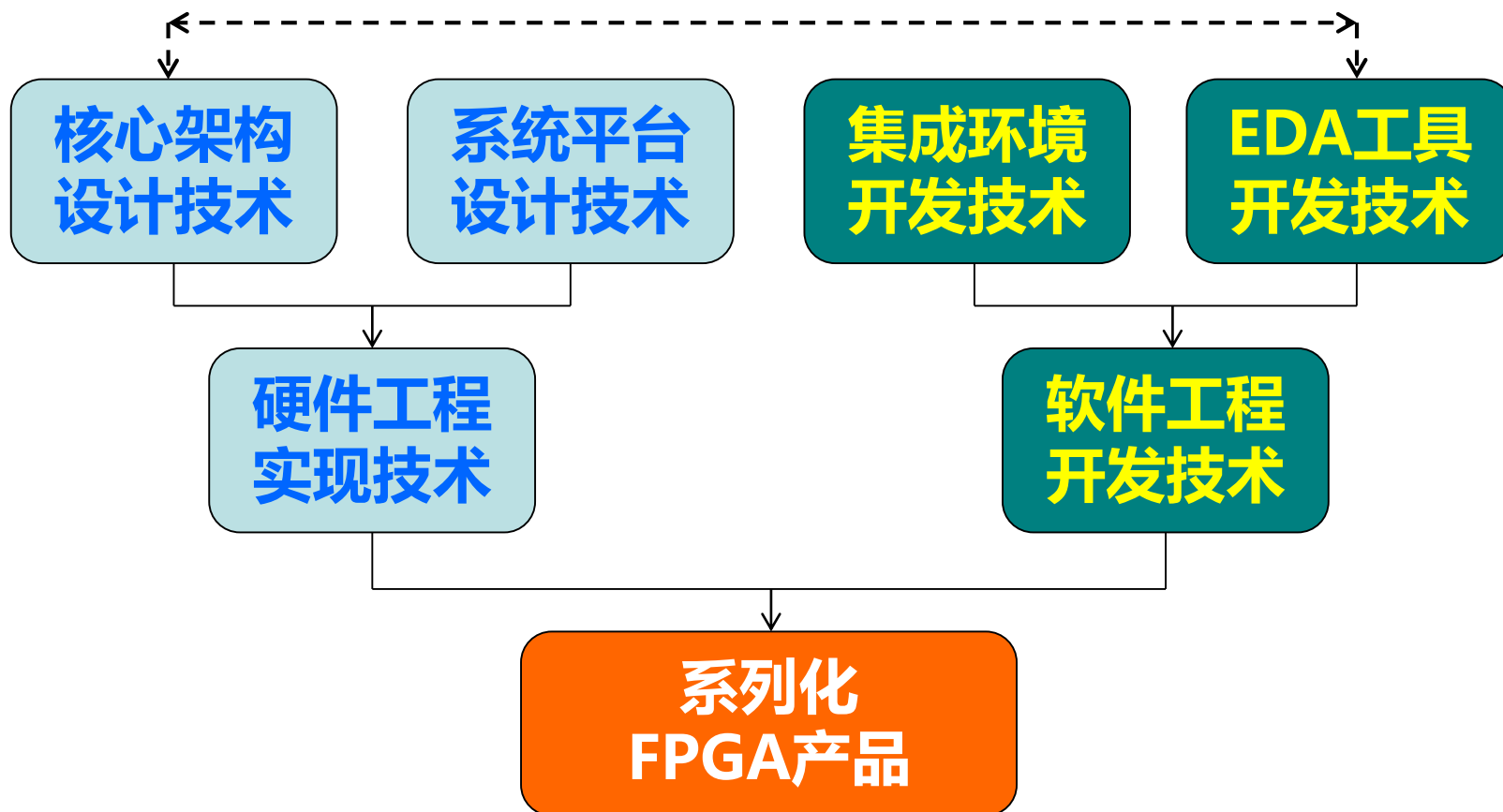
传统部分

Source: Xilinx Estimates

附录：中国FPGA厂商何去何从？



需要有系列化的FPGA产品



X/A/L公司的专利技术中50%以上是保护核心架构的专利！

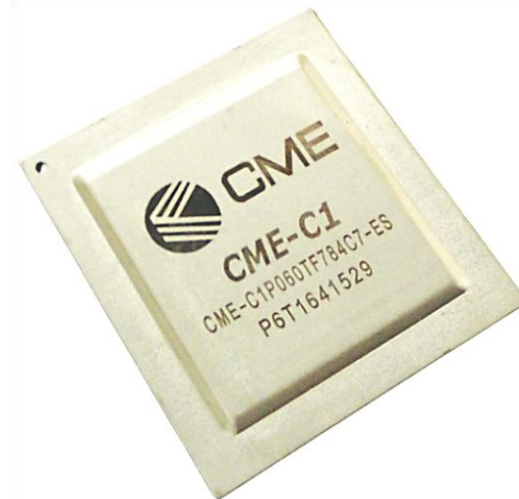
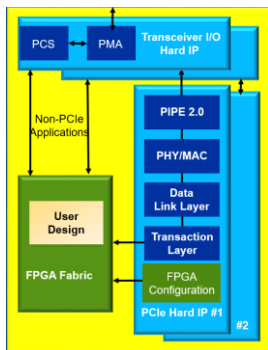
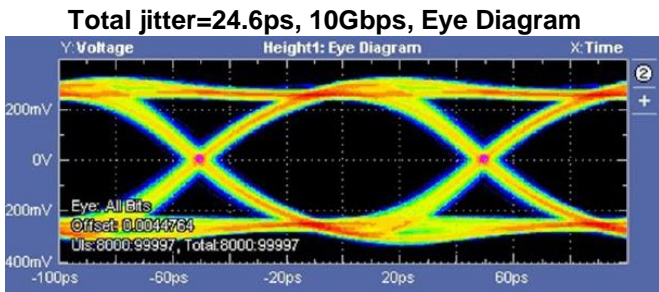
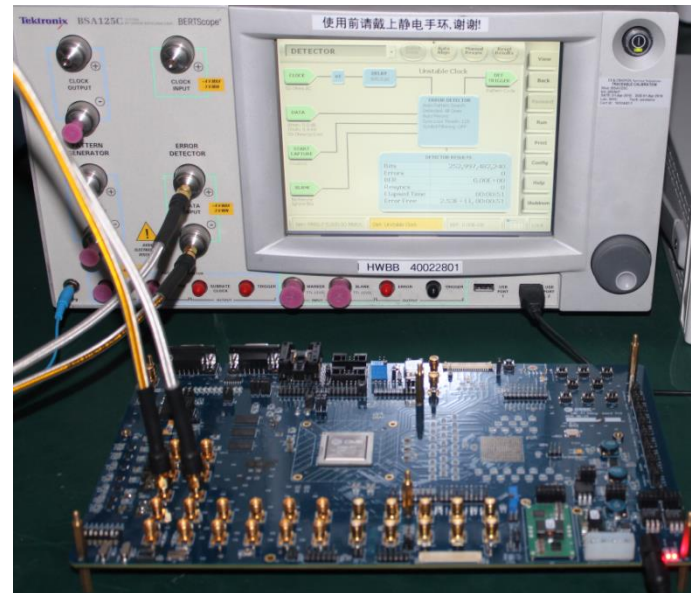
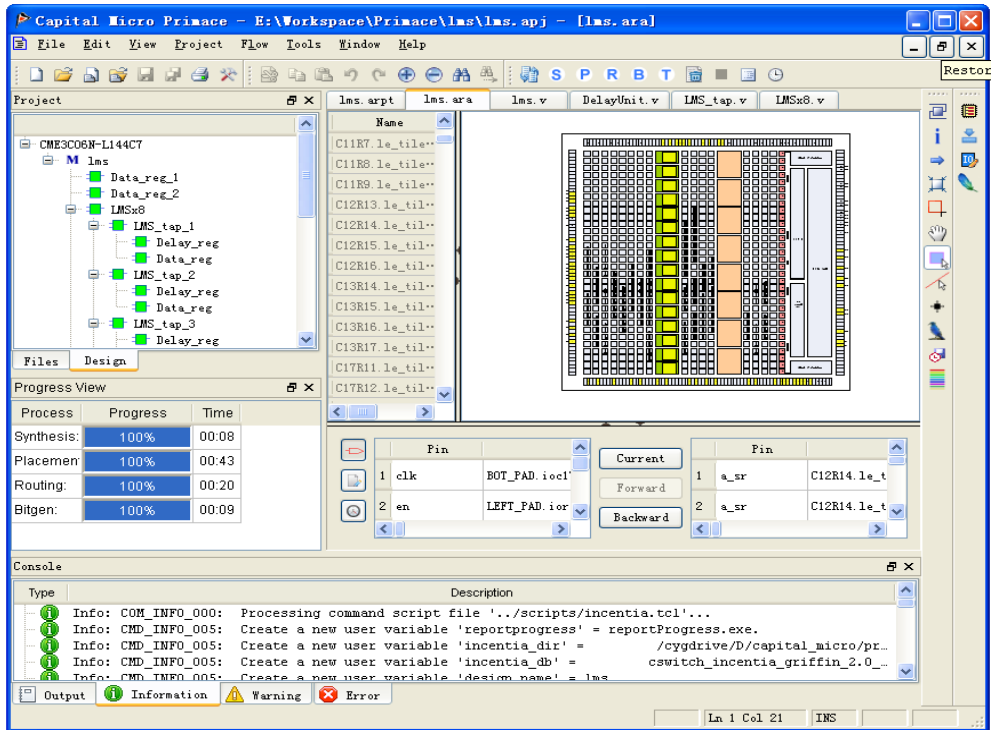
自主知识产权的FPGA产品，首先体现在具备自主研发可编程逻辑器件核心架构**的能力！**

自主知识产权的FPGA产品，其次体现在具备自主研发FPGA器件配套软件工具的能力！

- 用户易用性、友好性、面向应用的软IP库支持、以及EDA工具性能和成熟度方面

高端FPGA器件要想产业化，软件工具的好坏是决定性的因素！

CME-C1千万门级中高端国产FPGA问世



CME-C1芯片对标

	Altera	Xilinx	Lattice	Microsemi	CME
Part Number	EP4SGX70	XC6VLX75T	ECP5-45	M2S050	C1
Process	40nm TSMC	40nm UMC	40nm Fujitsu	65nm UMC	40nm TSMC
LUT Architecture	8 input LUT	6 input LUT	4 input LUT	4 input LUT	6 input LUT
Equivalent LUT4	73K	74.5K	44K	48.6K	57.6K
LUT6	N/A	46k	N/A	N/A	36K
REG	58K	93K	44K	48.6K	74K
LRAM	908Kbit	1045Kbit	351Kbit	N/A	576Kbit
EMB	6.4Mbit	5.6Mbit	1.944Mbit	1.826Mb	2.53Mbit
DSP (18x18)	384	288	72	72	288
PLL	4	6	4	6	4
IO	480	360	245	377	477
SerDes	16 (8.5Gbps)	12 (6.6Gbps)	4 (3.2Gbps)	8(5Gbps)	4 (10Gbps)
PCIe Gen2.0	YES	YES	NO	Yes	Yes
DDR3	1067Mbps	N/A	800Mbps	667Mbps	1333Mbps
LVDS Pair (Inputs/Outputs)	1.6Gbps (128)	1.3Gbps	800Mbps	700Mbps	1.3Gbps (144/144)
ADC	N/A	N/A	N/A	N/A	Dual 12 bit
Status	Production	Production	Production	Production	Production

路漫漫其修远兮 吾将上下而求索



京微雅格
Capital Microelectronics

谢谢！

hlwang@capital-micro.com



Confidential